



US 20240213058A1

(19) **United States**

(12) **Patent Application Publication**
Suwada et al.

(10) **Pub. No.: US 2024/0213058 A1**

(43) **Pub. Date: Jun. 27, 2024**

(54) **LOAD LOCK ARRANGEMENTS,
ASSOCIATED TEMPERATURE CONTROL
ASSEMBLIES, AND SEMICONDUCTOR
PROCESSING SYSTEMS INCLUDING LOAD
LOCK ARRANGEMENTS AND
TEMPERATURE CONTROL ASSEMBLIES**

Publication Classification

(51) **Int. Cl.**
H01L 21/67 (2006.01)
(52) **U.S. Cl.**
CPC .. H01L 21/67201 (2013.01); **H01L 21/67248**
(2013.01)

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(21) Appl. No.: **18/392,301**

(22) Filed: **Dec. 21, 2023**

Related U.S. Application Data

(60) Provisional application No. 63/476,985, filed on Dec.
23, 2022.

(57) **ABSTRACT**

Load lock assemblies and associated temperature control assemblies are disclosed. The temperature control assemblies are moveably disposed within a load lock chamber body and constructed and arranged to be inserted and extracted from the load lock chamber body.

